

# SOT1017-1

plastic low profile quad flat package; 176 leads; body 20 x 20 x 1.4 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	LQFP176
<b>Package type industry code</b>	LQFP176
<b>Package style descriptive code</b>	LQFP (low profile quad flat package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MS-026
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	20-8-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	19.8	-	20	20.2	mm
E	package width	19.8	-	20	20.2	mm
A	seated height	[tbd]	-	1.6	1.6	mm
A <sub>2</sub>	package height	1.35	-	1.4	1.45	mm
n <sub>2</sub>	actual quantity of termination	-	-	176	-	



2. Package outline

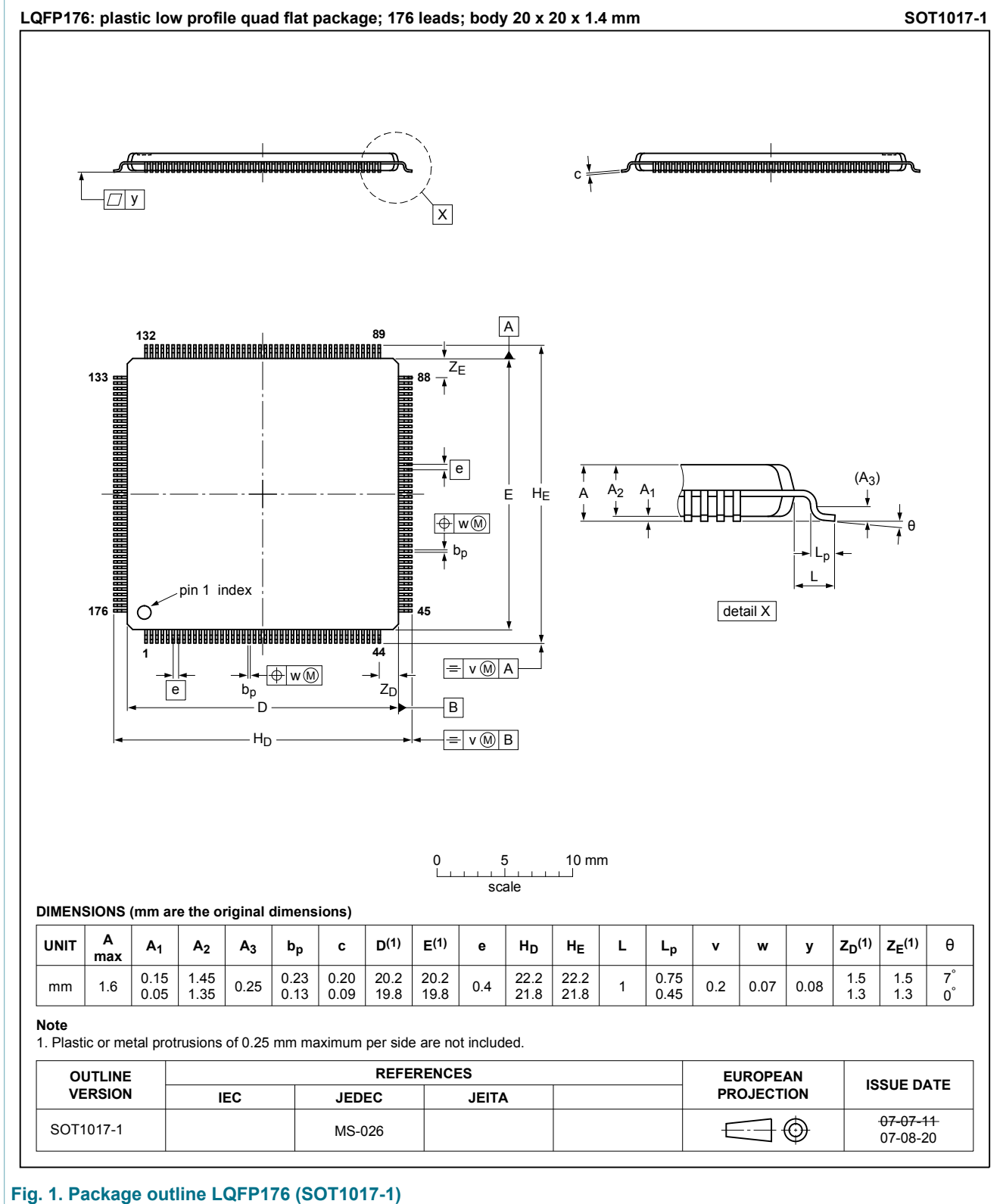


Fig. 1. Package outline LQFP176 (SOT1017-1)

### 3. Legal information

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